TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π-MOSV)

2SK3371

Switching Regulator Applications

Unit: mm

Features

- Low drain-source ON-resistance: R_{DS} (ON) = 6.4 Ω (typ.)
- High forward transfer admittance: $|Y_{fS}| = 0.85 \text{ S (typ.)}$
- Low leakage current: I_{DSS} = 100 μA (max) (V_{DSS} = 600 V)
- Enhancement mode: V_{th} = 2.0 to 4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	600	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$	V_{DGR}	600	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	1	Α	
	Pulse (Note 1)	I _{DP}	2	A	
Drain power dissipati	on (Tc = 25°C)	PD	20	W	
Single-pulse avalanche energy (Note 2)		Eas	56	mJ	
Avalanche current		I _{AR}	1	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	2	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

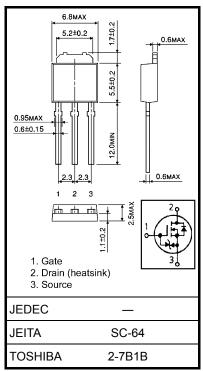
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	6.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	125	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

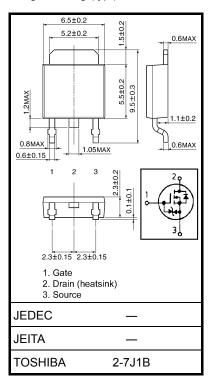
Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$, L = 100 mH, $I_{AR} = 1 \text{ A}$, $R_G = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by max channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.36 g (typ.)



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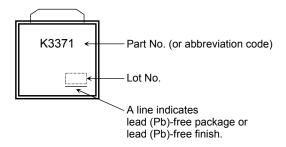
Electrical Characteristics (Ta = 25°C)

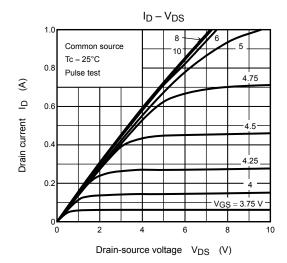
Chara	acteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Gate-source brea	kdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cutoff curre	nt	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μА
Drain-source brea	akdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold voltage		V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON-	-resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 0.5 A		6.4	9.0	Ω
Forward transfer	admittance	Y _{fS}	V _{DS} = 10 V, I _D = 0.5 A	0.4	0.85	_	S
Input capacitance Reverse transfer capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		190	_	pF
		C _{rss}			15	_	
Output capacitance		C _{oss}			55	_	
Switching time	Rise time	t _r	10 V	_	12	_	ns
	Turn-on time	t _{on}		_	55	_	
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}	Duty \leq 1%, $t_W = 10 \ \mu s$	_	90	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}$		9	_	nC
Gate-source charge		Q _{gs}			3.5		
Gate-drain ("Miller") charge		Q _{gd}		_	5.5	_	

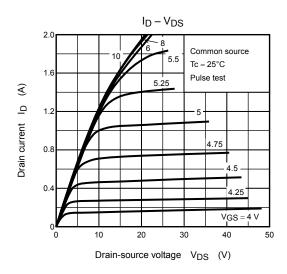
Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

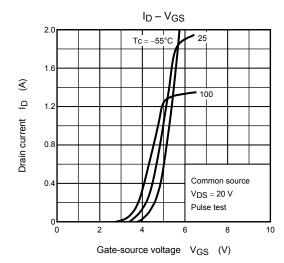
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current	I _{DR}	_	_	_	1	Α
Pulse drain reverse current	I _{DRP}	_	_	_	2	Α
Diode forward voltage	V _{DSF}	I _{DR} = 1 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 1 A, V _{GS} = 0 V,	_	400	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 100 A/μs	_	1.4	_	μС

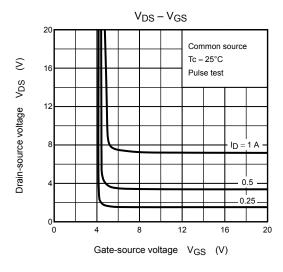
Marking

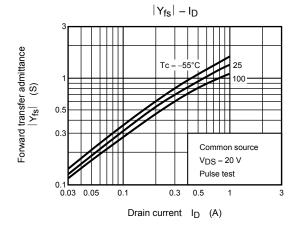


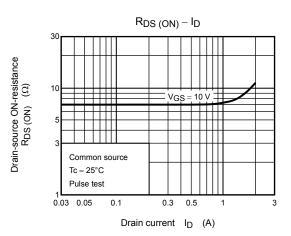




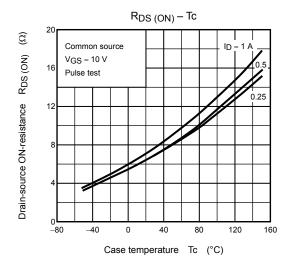


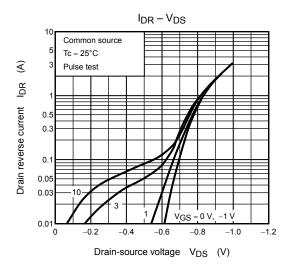


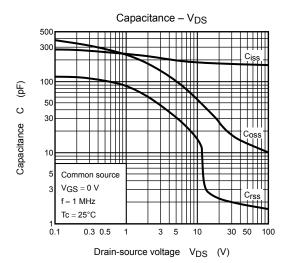


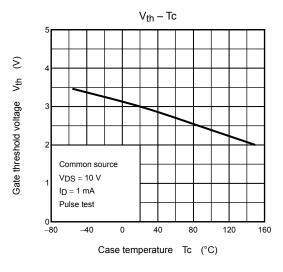


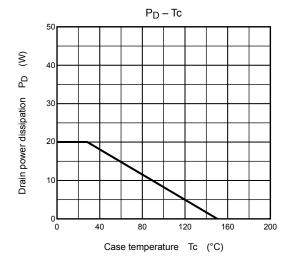
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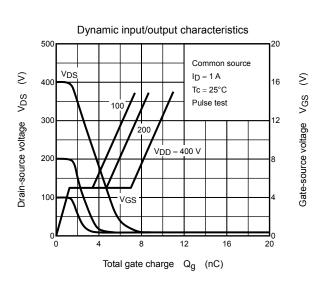


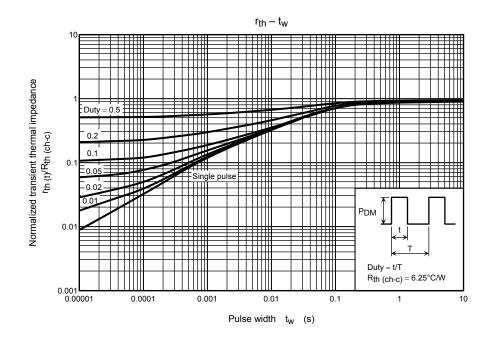


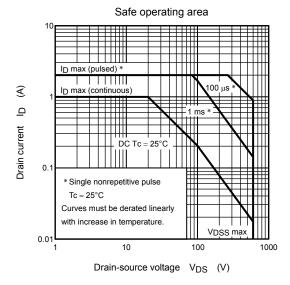


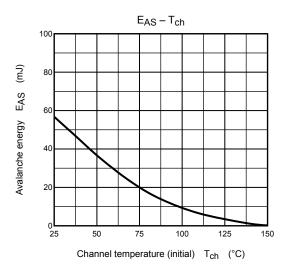


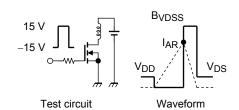












$$R_G = 25~\Omega$$
 $V_{DD} = 90~V,~L = 100~mH$

$$\mathsf{EAS} = \frac{1}{2} \cdot \mathsf{L} \cdot \mathsf{I}^2 \cdot \left(\frac{\mathsf{BVDSS}}{\mathsf{BVDSS} - \mathsf{VDD}} \right)$$

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